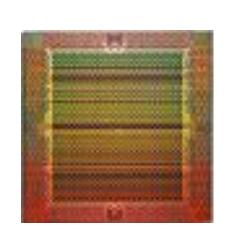
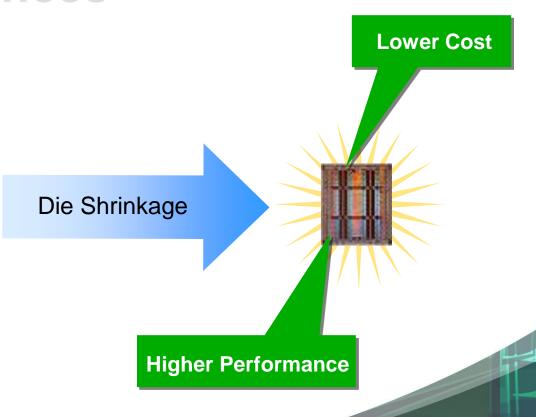
# Managing Technology Risk in 65 nm and Beyond



### **Expected Benefits of Semiconductor Process Advances**







#### Impact of Semiconductor Product Choices

- What features and capabilities to include
- Process maturity
- Design-formanufacturability
- Device check-out procedures
- Foundry partner



- Product delivery (onschedule vs. late)
- Product availability (improving yields vs. poor yields)
- Product quality and reliability



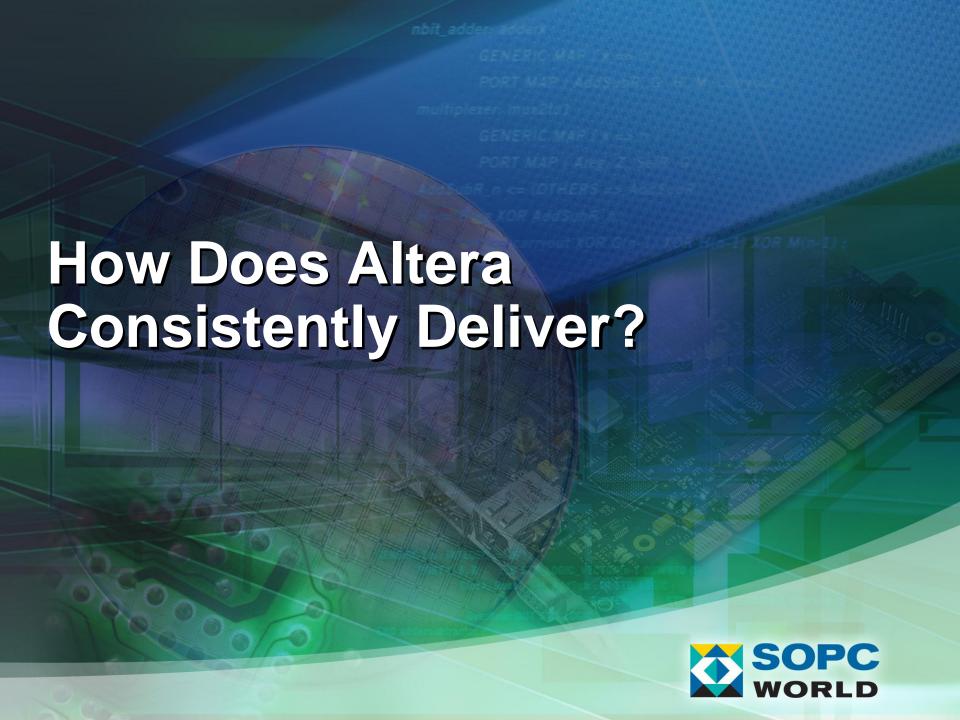
#### **Altera Meets Rollout Commitments**

	Altera® Device Family	First Prototypes	Months From First Prototypes to Production	Months Until All Devices Available
130 nm	Cyclone® FPGAs	December 2002	3	4
	Stratix® FPGAs	May 2002	5	10
	Stratix GX FPGAs	January 2003	10	7
90 nm	Cyclone II FPGAs	January 2005	3	7
	Stratix II FPGAs	June 2004	6	8
	Stratix II GX FPGAs	March 2006	8	N/A

The Right Technology Choices Deliver Predictable, Timely Results

The Wrong Choices Can Result in Delayed Rollouts, Limited Availability, and Product Recalls





#### What Really Matters to Altera's Customers

Increased productivity and risk reduction





Design

Requires Multidimensional Execution



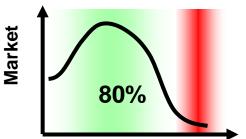
- 1. Precise investments in feature and capabilities
  - Intense research required to determine the right feature set that satisfies customer needs and results in a successful product



### **Precise Product Investment in Features and Capabilities**

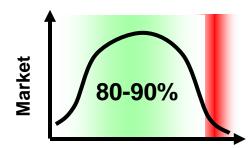
Core Performance • "More performance is always better"

- 20% designs above 250-MHz core performance
- Large cost and power penalties



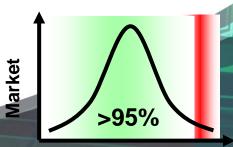
Memory Speed

- To achieve additional 10-20% market in performance means...
- Additional cost 30-40%
- Additional risks with signal integrity



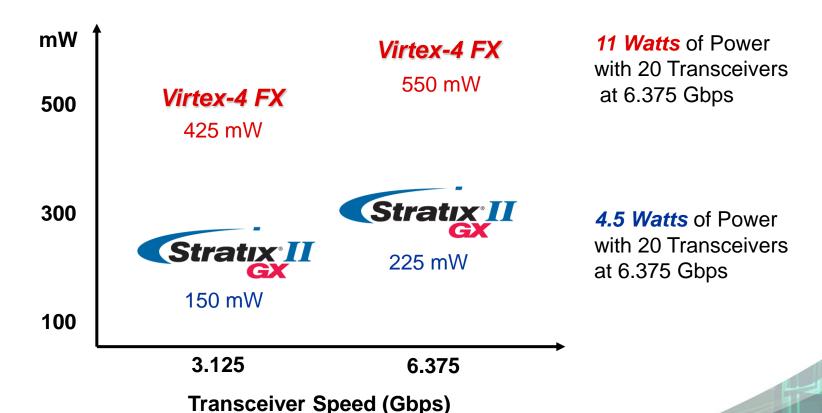
Serial Interface

- > 95% FPGA 155 MHz to 6.5 GHz
- Additional 5% carries risk, cost, and power penalties





### **Aggressiveness Is Not Free**



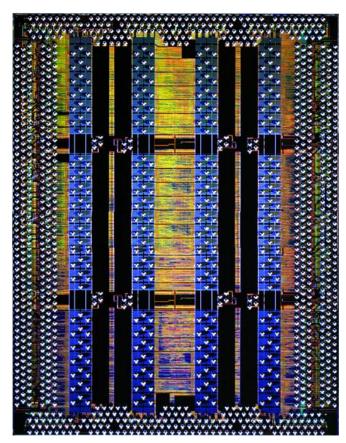
Benefit of Band-Optimizing Technology for 622 Mbps - 6.375 Gbps



- 1. Precise investment in features and capabilities
- 2. Industry's most comprehensive test chip program
  - Early collaboration on process development and design verification enables reliable new product delivery



## Industry's Most Comprehensive Test Chip Plan



Altera Test Chips

Early Technology Assessment

Feasibility Testing

Circuit and Feature Validation

Routing Structure Confirmation

**Architectural Verification** 

Design Optimization and Refinement



### Altera's Eleven 65-nm Test Chips

Test Chips	Tape Out
TC1	Q2 2003
TC2	Q3 2004
TC3A	Q2 2005
TC3B	Q2 2005
TC4	Q3 2005
TC5A	Q3 2005
TC5B	Q3 2005
TC6A	Q4 2005
TC6B	Q4 2005
TC7	Q1 2006
TC8	Q2 2006

Comprehensive Test Chip Program
Identifies and Resolves Issues Before
Product Introduction

- 1. Precise investment in features and capabilities
- 2. Industry's most comprehensive test chip program
- 3. Rigorous device check-out procedures
  - Methodical and thorough check-out procedures help identify and resolve issues before products are released to customers



#### Altera's Rigorous 8-Step Product Checkout

- 1. IC design ensures design meets function, performance, and power specifications.
- 2. CAD and layout ensure that mask meets Altera's and TSMC's mask rules.
- 3. Cross-functional teams perform design-formanufacturability (DFM) analysis to ensure robust manufacturing.
- 4. TSMC checks masks for high-volume, high-yield manufacturability.



#### Altera's Rigorous 8-Step Product Checkout

- 5. Altera and TSMC check transistor characteristics, layer thicknesses, line widths and resistances, etc.
- Product engineering characterizes wafers and packaged units, gives feedback to improve yield.
- Applications engineering exercises device from user perspective.
- 8. Reliability group ensures quality of final product before it is shipped to customers.



- 1. Precise investment in features and capabilities
- 2. Industry's most comprehensive test chip program
- 3. Rigorous device check-out procedures
- 4. Unique patented redundancy technology
  - Unique Altera technology provides 7x to 8x yield improvement early in process life cycle
  - One of many DFM techniques Altera employs



### **Patented Redundancy Technology**

Patented
Redundancy
Technology
Used Since
1993

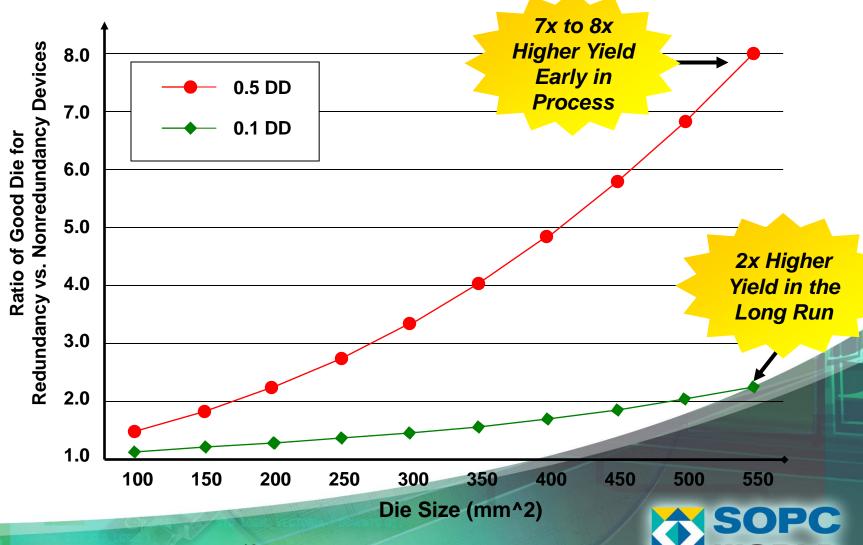
High-Density FPGA

Column
With Defect
Deactivated

Redundant Column Activated

Altera's 7<sup>th</sup>-Generation Patented Redundancy Technology Improves Yields

### Redundancy Enables Predictable Manufacturability



- 1. Precise investment in features and capabilities
- 2. Industry's most comprehensive test chip program
- 3. Rigorous device check-out procedures
- 4. Patented redundancy technology
- 5. Focused foundry partnership
  - Industry's longest and stronger foundry partnership
  - Accelerates improvement in yield, improves supply



### **Altera's Foundry Partner: TSMC**

- TSMC leads the foundry industry
  - Over 50% market share
  - Annual R&D investment 55% greater than nearest competitor
  - Leader in DFM and lithography
  - Longest-running mask making facility
- Semiconductor industry leaders are driving TSMC's 65-nm process to success











#### The Industry's Strongest Foundry Partnership

#### **Benefit to**



#### **What Altera Gets:**

Access to most advanced process without huge R&D investments

Pure play foundry—no capacity conflict

Mutual benefit of an exclusive relationship

Ability to get process tuned to its needs

#### **Benefit to**



#### FPGA Structure

Memory structure
Large dies
Dense interconnect
High performance

#### **What TSMC Gets:**

Defect identification
Defect density reduction
Back-end improvements
Front-end improvements

Focused Partnership of Industry Leaders Drives Both to Success

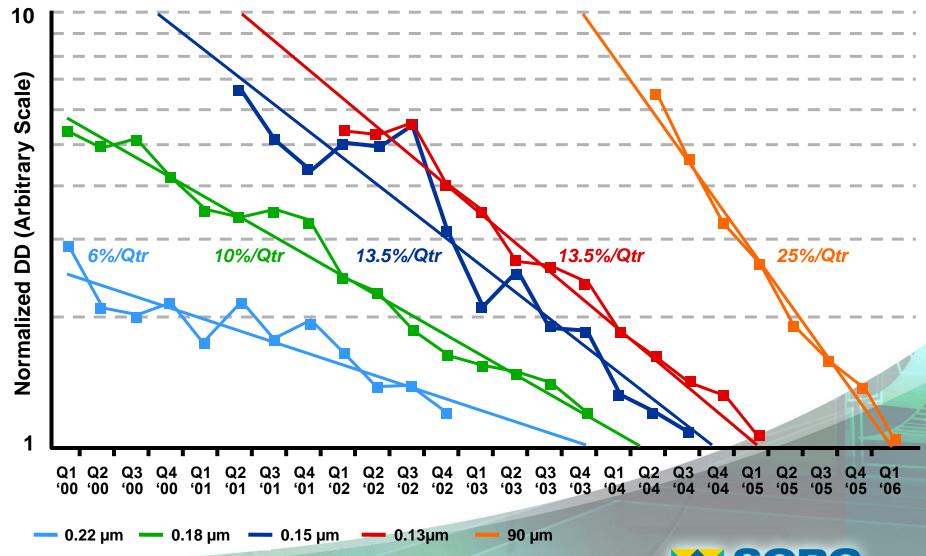


#### **Benefits of Focused Foundry Partnership**

- Better product availability
  - Total wafer volume through single foundry maximizes yield enhancement
  - Eliminates inefficiency of multiple foundries, simplifies supply chain
- Streamlined inventory management
  - Multiple foundries may require managing multiple codes for "same" device
- Fewer device qualifications
  - Single characterization effort
  - Eliminates need to do qualifications for more than one foundry
- Consistent product performance characteristics
  - One manufacturing process produces the most uniform results
  - Avoids inconsistencies arising from multiple mask sets among multiple foundries



#### **Altera-TSMC Record of Defect Density Reduction**





#### Conclusion

- Altera makes technology choices aimed at successfully delivering products to customers
- Altera has the best industry record of reliably delivering the benefits of new semiconductor process technology
- Metrics for our mutual success:
  - Meeting commitments to deliver new products on schedule
  - Achieving smooth ramps to volume production
  - Resolving product issues before product introduction

Altera Products Fulfill the Promise of Increased Productivity and Minimized Risk



